

**Maximum Ratings** (@T<sub>A</sub> = 25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit	Conditions
Peak Pulse Power Dissipation	P <sub>PP</sub>	300	W	8/20μs, Per Fig. 3
Peak Pulse Current	I <sub>PP</sub>	12	A	8/20μs, Per Fig. 3
ESD Protection – Contact Discharge	V <sub>ESD Contact</sub>	±8	kV	Standard IEC 61000-4-2(ESD)
ESD Protection – Air Discharge	V <sub>ESD Air</sub>	±15	kV	Standard IEC 61000-4-2(ESD)
Electrical Fast Transient Current	I <sub>EFT</sub>	40	A	Standard IEC 61000-4-4(EFT)

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Package Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = 25°C unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
Reverse Working Voltage	V <sub>RWM</sub>	-	-	12.0	V	-
Reverse Current (Note 6)	I <sub>R</sub>	-	-	1.0	μA	V <sub>R</sub> = V <sub>RWM</sub> = 12.0V
Reverse Breakdown Voltage	V <sub>BR</sub>	13.3	-	15.75	V	I <sub>R</sub> = 1mA
Reverse Clamping Voltage	V <sub>CL</sub>	-	-	19	V	I <sub>PP</sub> = 1A, t <sub>p</sub> = 8/20μs
Capacitance	C <sub>T</sub>	-	95	-	pF	V <sub>R</sub> = 0V, f = 1MHz, Pin 1 to 3

Notes: 5. Device mounted on FR-4 PCB pad layout (2oz copper) as shown on Diodes, Inc. suggested pad layout AP02001, which can be found on our website at <http://www.diodes.com>.  
 6. Short duration pulse test used to minimize self-heating effect.

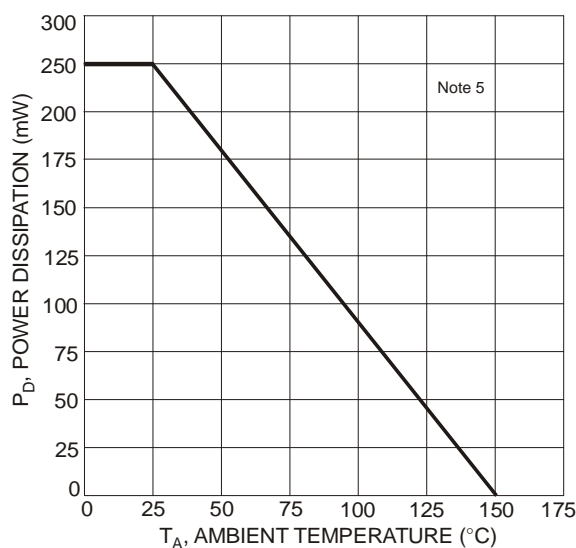


Figure 1 Power Derating Curve

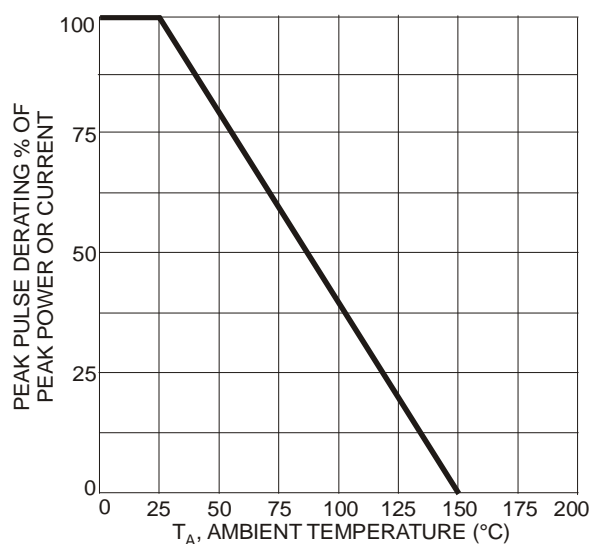


Figure 2 Power Dissipation vs. Ambient Temperature

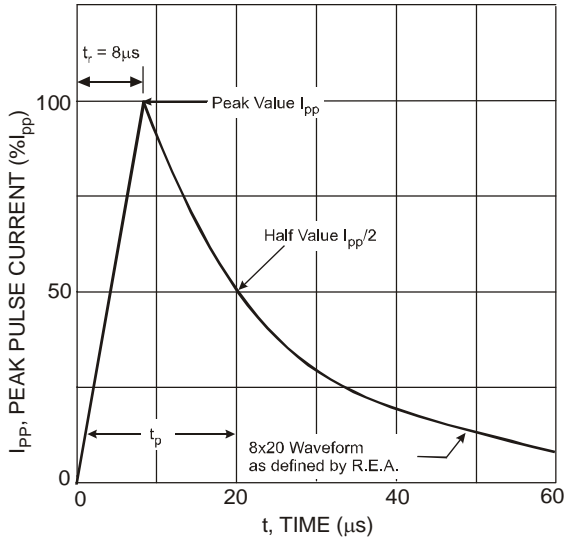


Figure 3 Pulse Waveform

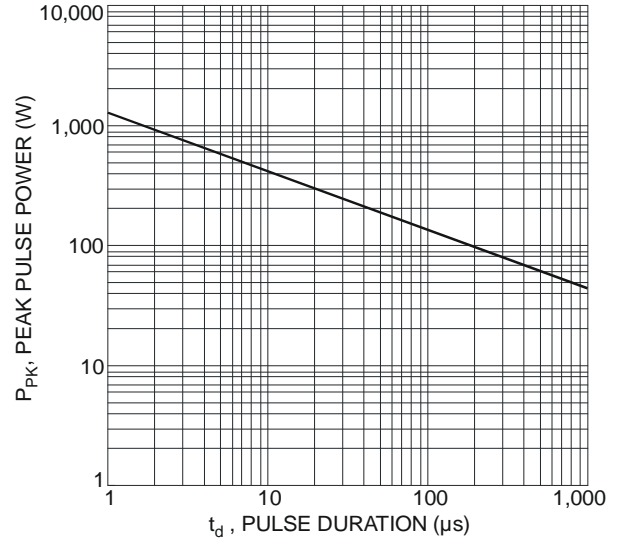


Figure 4 Max. Peak Pulse Power vs. Pulse Duration

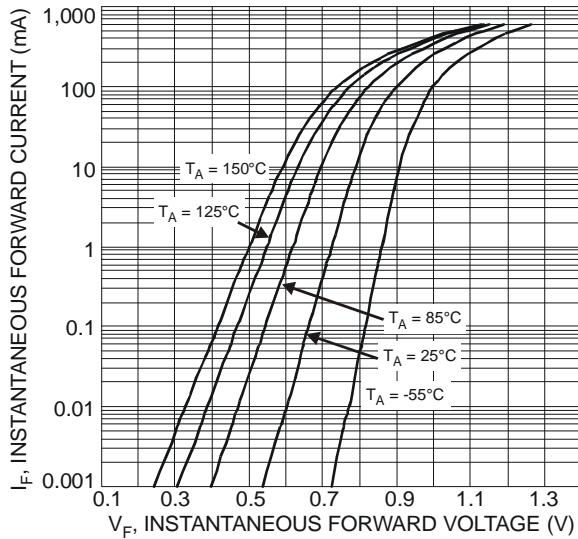


Figure 5 Typical Forward Characteristics

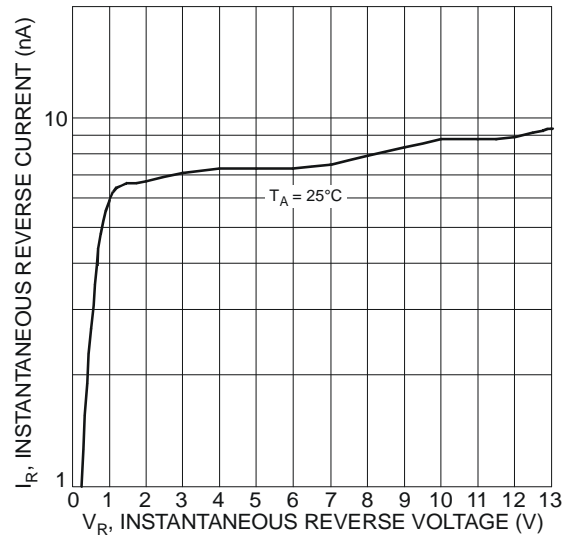


Figure 6 Typical Reverse Characteristics

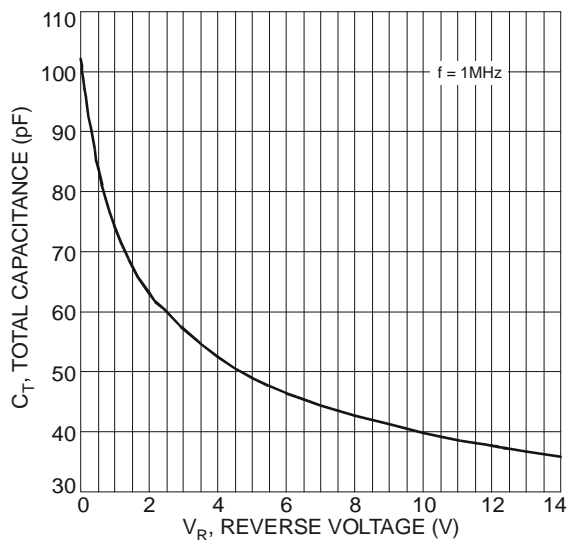
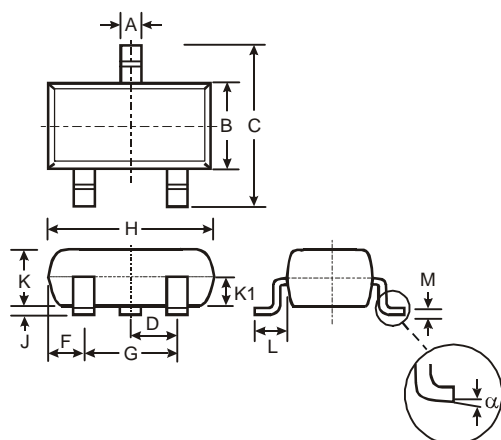


Figure 7 Typical Total Capacitance vs. Reverse Voltage

## Package Outline Dimensions

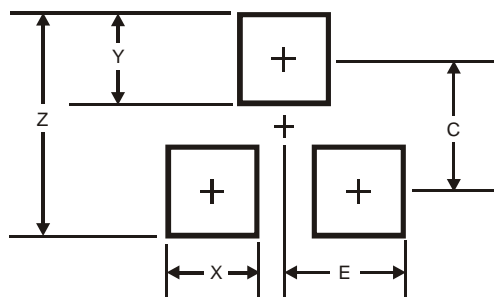
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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